

# 10V Drive Nch MOSFET

# RCD080N25

### Structure

Silicon N-channel MOSFET

### Features

- 1) Low on-resistance.
- 2) High-speed switching.
- 3) Wide range of SOA.
- 4) Drive circuits can be simple.
- 5) Parallel use is easy.

# Application

Switching

### Packaging specifications

	• .	
	Package	Taping
Type	Code	TL
	Basic ordering unit (pieces)	2500
RCD080N2	0	

## • Absolute maximum ratings (Ta = 25°C)

Paramete	Symbol	Limits	Unit	
Drain-source voltage		$V_{\rm DSS}$	250	V
Gate-source voltage		$V_{GSS}$	±30	V
Drain current	Continuous	I <sub>D</sub> *3	±8	Α
Dialii cuiteiit	Pulsed	I <sub>DP</sub> *1	±32	Α
Source current	Continuous	l <sub>S</sub> *3	8	Α
(Body Diode)	Pulsed	I <sub>SP</sub> *1	32	Α
Avalanche current		I <sub>AS</sub> *2	4	Α
Avalanche energy		E <sub>AS</sub> *2	4.67	mJ
Power dissipation		P <sub>D</sub> *4	85	W
Channel temperature	Tch	150	°C	
Range of storage temper	Tstg	-55 to +150	°C	

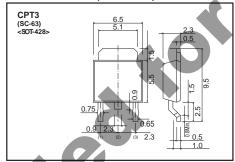
<sup>1</sup> Pw≦10μs, Duty cycle≤1%

### • Thermal resistance

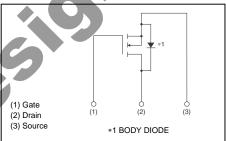
Parameter	Symbol	Limits	Unit
Channel to Case	Rth (j-c) *	1.46	°C/W

<sup>\*</sup> T<sub>C</sub>=25°C

### Dimensions (Unit : mm)



# • Inner circuit



<sup>\*2</sup> L  $\stackrel{\bullet}{=}$  500 $\mu$ H,  $V_{DD}$ =50V,  $R_G$ =25 $\Omega$ ,  $T_{ch}$ =25 $^{\circ}$ C

<sup>\*3</sup> Limited only by maximum channel temperature allowed.

<sup>\*4</sup> T<sub>C</sub>=25°C

<sup>\*</sup> Limited only by maximum channel temperature allowed.

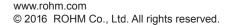
### • Electrical characteristics (Ta = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	$I_{GSS}$	-	-	±100	nΑ	$V_{GS}=\pm30V, V_{DS}=0V$
Drain-source breakdown voltage	$V_{(BR)DSS}$	250	-	-	V	I <sub>D</sub> =1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	1	-	10	μA	V <sub>DS</sub> =250V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS (th)</sub>	3	-	5	٧	V <sub>DS</sub> =10V, I <sub>D</sub> =1mA
Static drain-source on-state resistance	R <sub>DS (on)</sub>	-	225	300	mΩ	I <sub>D</sub> =4A, V <sub>GS</sub> =10V
Forward transfer admittance	I Y <sub>fs</sub> I*	2.7	-	-	S	$V_{DS}$ =10V, $I_{D}$ =4A
Input capacitance	C <sub>iss</sub>		1440	-	pF	V <sub>DS</sub> =25V
Output capacitance	C <sub>oss</sub>	-	80	-	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>		40	-	pF	f=1MHz
Turn-on delay time	t <sub>d(on)</sub> *	1	30	-	ns	V <sub>DD</sub> ≒125V, I <sub>D</sub> =4A
Rise time	t <sub>r</sub> *	-	40	-	ns	V <sub>GS</sub> =10V
Turn-off delay time	t <sub>d(off)</sub> *	1	40	-	ns	$R_L = 31.25\Omega$
Fall time	t <sub>f</sub> *	-	15	-	ns	$R_{G}=10\Omega$
Total gate charge	Q <sub>g</sub> *	-	25		nC	V <sub>DD</sub> ≒125V, I <sub>D</sub> =8A
Gate-source charge	Q <sub>gs</sub> *	-	10	-	nC	V <sub>GS</sub> =10V
Gate-drain charge	Q <sub>gd</sub> *	-	10	-	nC	

<sup>\*</sup>Pulsed

### ●Body diode characteristics (Source-Drain)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward Voltage	V <sub>SD</sub> *	-	<u>-</u>	1.5	V	$I_s$ =8A, $V_{GS}$ =0V
*Pulsed				O	7	
	0		N			
	-					
	•					



### ●Electrical characteristic curves (Ta=25°C)

Fig.1 Typical Output Characteristics ( I )

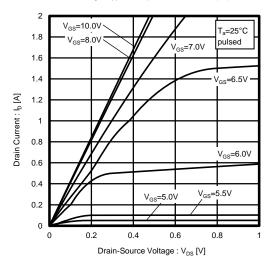


Fig.3 Typical Transfer Characteristics

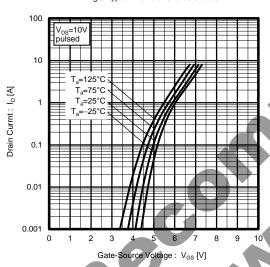


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

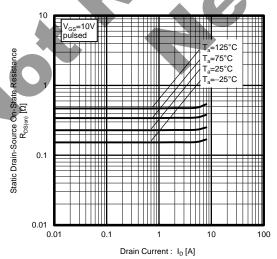


Fig.2 Typical Output Characteristics ( II )

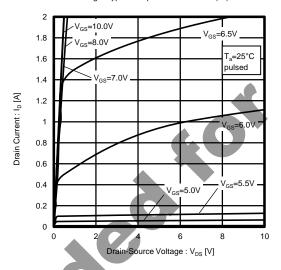


Fig.4 Gate Threshold Voltage vs. Channel Temperature

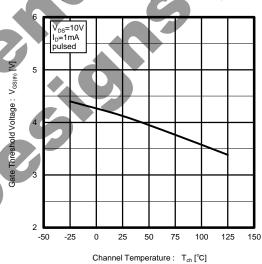
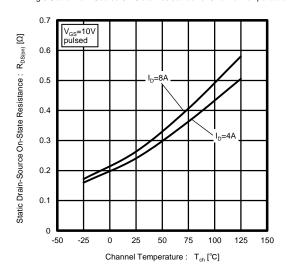


Fig.6 Static Drain-Source On-State Resistance vs. Channel Temperature



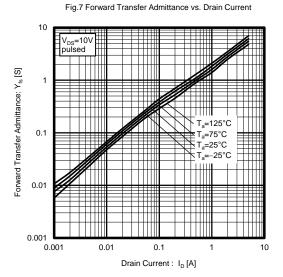


Fig.8 Source Current vs. Source-Drain Voltage

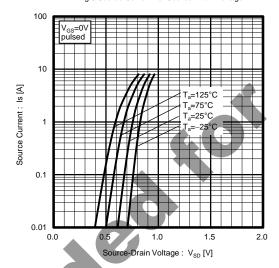


Fig.9 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

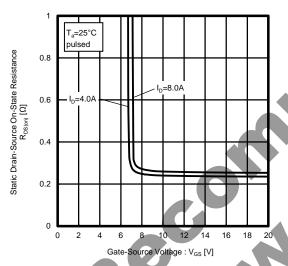


Fig.10 Switching Characteristic

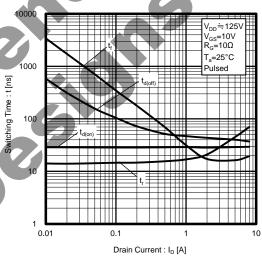


Fig.11 Dynamic Input Characteristics

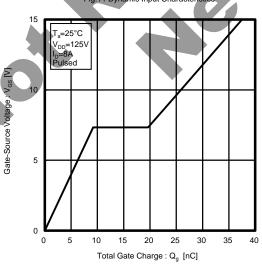
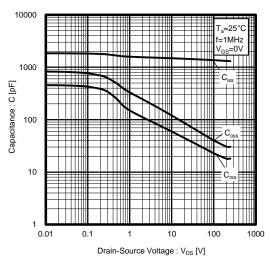


Fig.12 Typical Capacitance vs. Drain-Source Voltage



### Measurement circuits

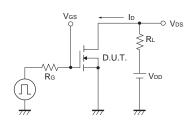


Fig.1-1 Switching Time Measurement Circuit

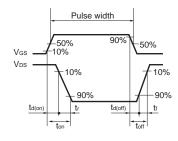


Fig.1-2 Switching Waveforms

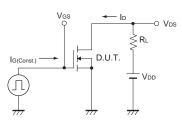


Fig.2-1 Gate Charge Measurement Circuit

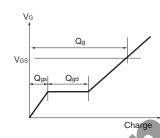


Fig.2-2 Gate Charge Waveform

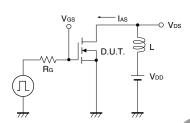


Fig.3-1 Avalanche Measurement Circuit

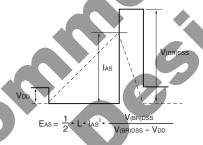


Fig.3-2 Avalanche Waveform

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